

GENERAL DESCRIPTION

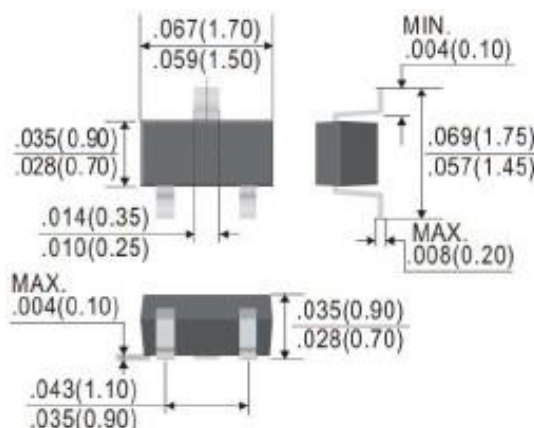
The ME2N7002KWT-G is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits , and low in-line power loss are needed in a very small outline surface mount package.

FEATURES

- $R_{DS(ON)} \leq 3\Omega @ V_{GS}=10V$
- $R_{DS(ON)} \leq 4\Omega @ V_{GS}=4.5V$
- ESD Protected up to 2kV
- Low on resistance RDS(ON)
- Low gate threshold voltage
- Low input capacitance

PIN CONFIGURATION

SOT-523

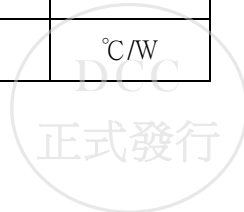


Ordering Information: ME2N7002KWT-G (Green product-Halogen free)

Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

Parameter	Symbol	Maximum Ratings	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain	I _D	300	mA
Pulsed Drain Current	I _{DM}	1	A
Maximum Power Dissipation* (Steady State)	P _D	150	mW
Operating Junction Temperature	T _J	- 55 to + 150	°C
Thermal Resistance-Junction to Ambient*	R _{θJA}	833	°C/W

* Surface-mounted on FR4 board using 1 in sq pad size



Electrical Characteristics ($T_A=25^\circ\text{C}$ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=10\ \mu\text{A}$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$	1		2.5	V
I_{GSS}	Gate-Body Leakage	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 10	μA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60\text{V}$			1	μA
$R_{DS(ON)}$	Drain-Source On-Resistance*	$V_{GS}=10\text{V}, I_D=500\text{mA}$			3	Ω
		$V_{GS}=4.5\text{V}, I_D=200\text{mA}$			4	
V_{SD}	Diode Forward Voltage	$I_S=0.5\text{A}, V_{GS}=0\text{V}$		0.85		V
DYNAMIC						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=0.5\text{A}$		0.44		nC
Q_{gs}	Gate-Source Charge			0.2		
Q_{gd}	Gate-Drain Charge			0.1		
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		22.5	50	pF
C_{oss}	Output Capacitance			9	25	
C_{rss}	Reverse Transfer Capacitance			7.5	10	
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=30\text{V}, V_{GS}=10\text{V}, R_G=25\Omega, I_D=0.5\text{A}$		2.7		ns
t_r	Turn-On Rise Time			2.5		
$t_{d(off)}$	Turn-Off Delay Time			13		
t_f	Turn-Off Fall Time			8		

Notes: a, pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$, Guaranteed by design, not subject to production testing.

b. Force mos reserves the right to improve or change product design, functions, reliability, qualified manufacturer without notice



Typical Characteristics (T_J =25°C Noted)

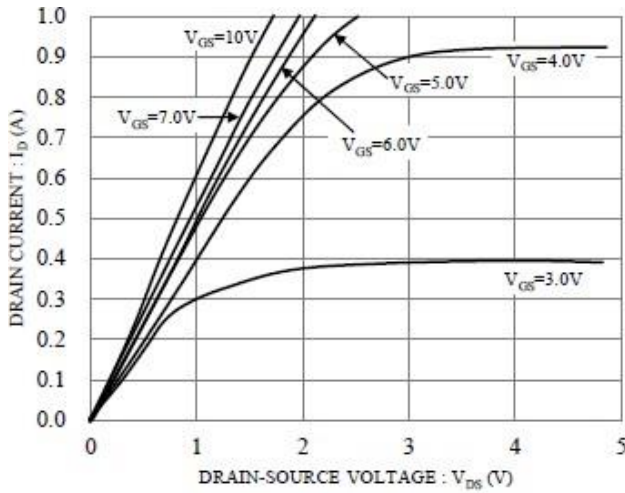


Fig.1 Typical output characteristics

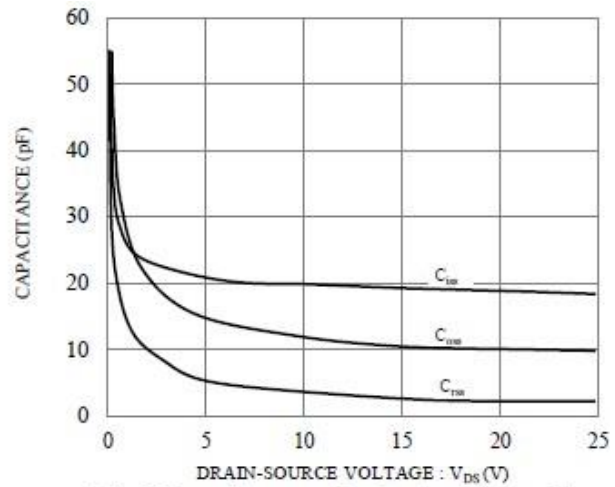


Fig.2 Capacitance vs Drain-to-source voltage

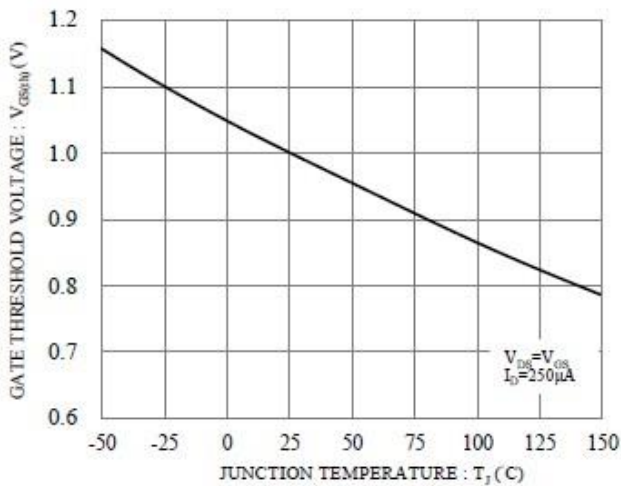


Fig.3 Gate threshold voltage vs. Junction temperature

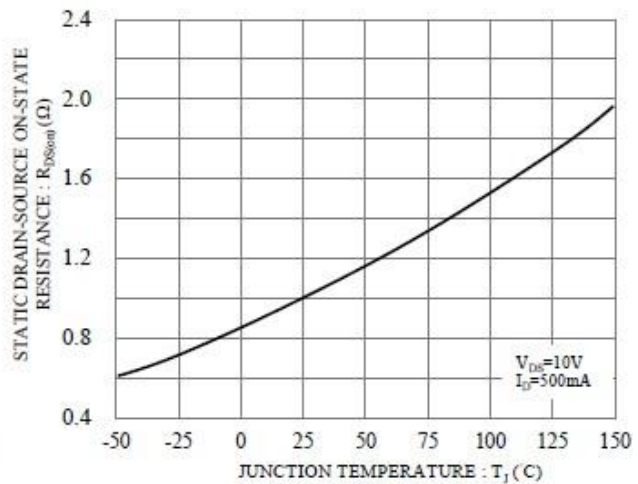


Fig.4 On-State Resistance vs. Junction temperature

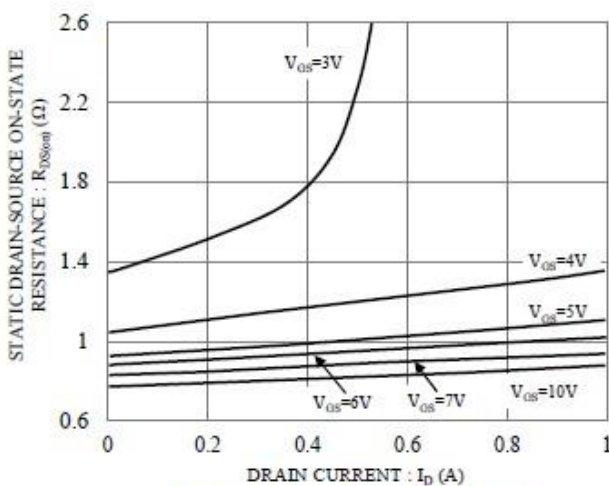


Fig.5 Static drain-source on-state resistance vs. Drain current

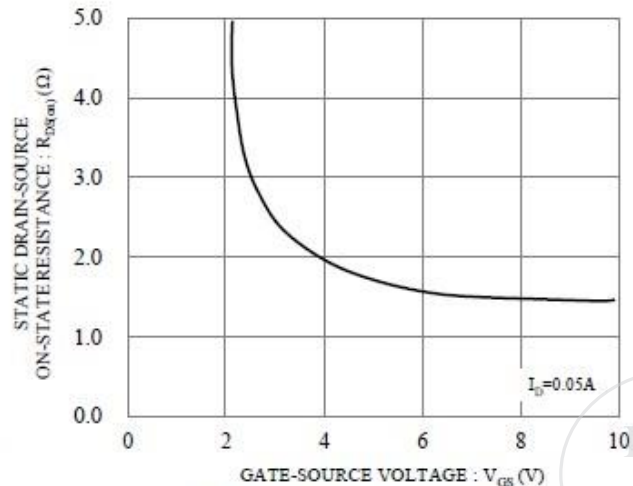
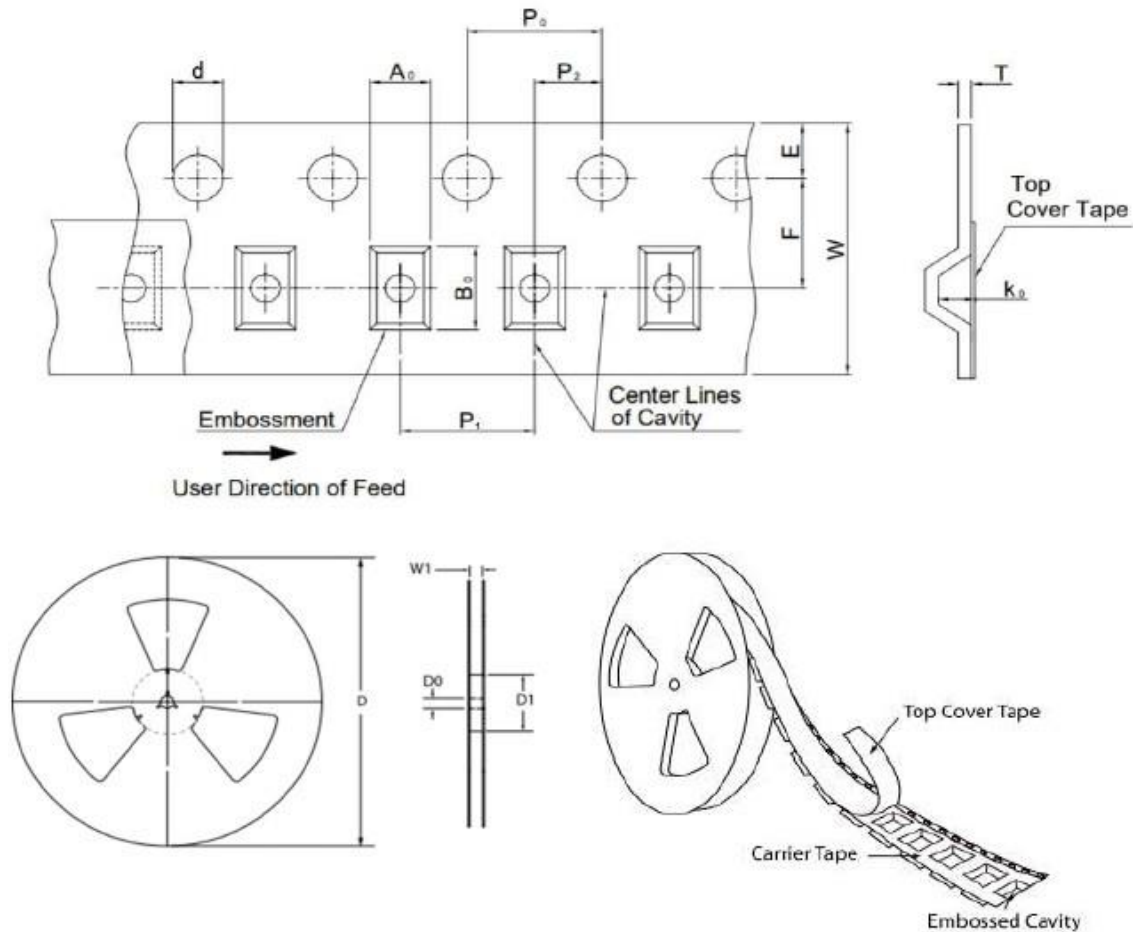


Fig.6 Static drain-source on-state resistance vs. Gate-source voltage



TAPE & REEL SPECIFICATION



Item	Symbol	SOT-523
Carrier width	A ₀	1.90 ± 0.10
Carrier length	B ₀	1.95 ± 0.10
Carrier depth	K ₀	1.10 ± 0.10
Sprocket hole	d	1.50 ± 0.10
Reel outside diameter	D	178.00 ± 2.00
Feed hole width	D ₀	13.00 ± 0.50
Reel inner diameter	D ₁	MIN. 50.00
Sprocket hole position	E	1.75 ± 0.10
Punch hole position	F	3.50 ± 0.10
Sprocket hole pitch	P ₀	4.00 ± 0.10
Punch hole pitch	P ₁	4.00 ± 0.10
Embossment center	P ₂	2.00 ± 0.10
Overall tape thickness	T	MAX. 0.60
Tape width	W	8.00 ± 0.30
Reel width	W1	MAX. 10.00



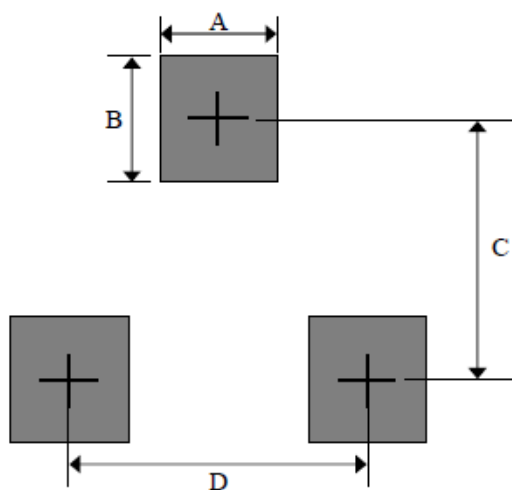
ORDER INFORMATION

Package	Reel Size	Quantity
SOT-523	7"	4,000

ORDER INFORMATION

Part Number	Marking Code
ME2N7002KWT-G	MP

SUGGESTED SOLDER PAD LAYOUT



Unit : mm

PACKAGE	A	B	C	D
SOT-523	0.70	0.70	1.30	1.00

